

Title (en)  
HEATING SYSTEM

Title (de)  
HEIZSYSTEM

Title (fr)  
SYSTÈME DE CHAUFFAGE

Publication  
**EP 2299777 A1 20110323 (EN)**

Application  
**EP 08761562 A 20080507**

Priority  
• ES 2008000317 W 20080507  
• ES 200800901 U 20080430

Abstract (en)  
Heating system comprising an electric heater with a laminar structure formed by an extractable plate provided with an electricity conductive layer and a radiant heat-emitting layer that emits radiant heat when an electric heat source is applied by way of an electric circuit of multiple conductor cables within the heating layer, being provided with means for regulating the intensity of the radiant heat emitted and means for rapid installation/extraction, in such a way that the radiant heat-emitting layer can be maintained at a temperature of 80-110°C with an energy density of 750-800 w/m<sup>2</sup>. Thus, a highly-efficient heating system based on infrared radiation is obtained, allowing an energy saving that can reach 30%, and up to 50% in areas with large losses of air or in partially open spaces, therefore an economic saving.

IPC 8 full level  
**H05B 3/26** (2006.01); **F24C 7/04** (2006.01)

CPC (source: EP US)  
**F24C 7/043** (2013.01 - EP US); **H05B 3/26** (2013.01 - EP US); **H05B 2203/014** (2013.01 - EP US); **H05B 2203/017** (2013.01 - EP US); **H05B 2203/032** (2013.01 - EP US)

Citation (third parties)  
Third party :  
• KR 100800119 B1 20080131  
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Cited by  
EP3756452A3; FR3097720A1; FR3097942A1; EP3756456A3; FR3097941A1

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